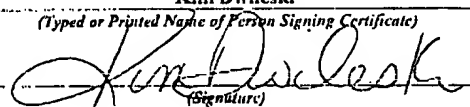


<b>CERTIFICATE OF TRANSMISSION BY FACSIMILE (37 CFR 1.8)</b>		Docket No. <b>END920010002US1</b>	
Applicant(s): Ray et al.			
Serial No. <b>09/779,812</b>	Filing Date <b>2/8/2001</b>	Examiner <b>Nguyen, Ha T.</b>	Group Art Unit <b>2812</b>
Invention: <b>LEAD-FREE SOLDER STRUCTURE AND METHOD FOR HIGH FATIGUE LIFE</b>			
<p>I hereby certify that this <u>Amendment (19 pages)</u></p> <p style="text-align: center;"><small>(Identify type of correspondence)</small></p> <p>is being facsimile transmitted to the United States Patent and Trademark Office (Fax. No. <u>703-308-7722</u>)</p> <p>on <u>8/15/2003</u></p> <p style="text-align: center;"><small>(Date)</small></p> <p style="text-align: right;"><u>Kim Dwileski</u></p> <p style="text-align: center;"><small>(Typed or Printed Name of Person Signing Certificate)</small></p> <p style="text-align: center;"></p> <p style="text-align: center;"><small>(Signature)</small></p>			
<p><b>Note: Each paper must have its own certificate of mailing.</b></p>			
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